

isc N-Channel MOSFET Transistor

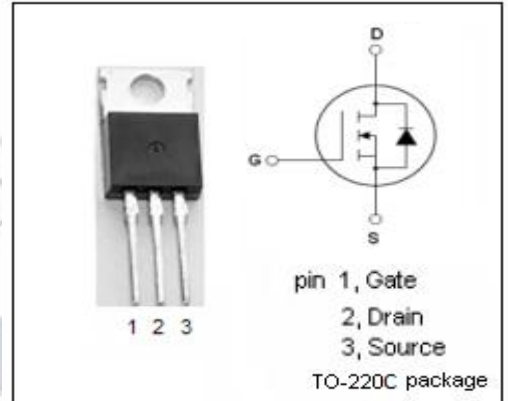
IPP200N15N3,IIPP200N15N3

• FEATURES

- Static drain-source on-resistance:
 $R_{DS(on)} \leq 20m\Omega$
- Enhancement mode
- Fast Switching Speed
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

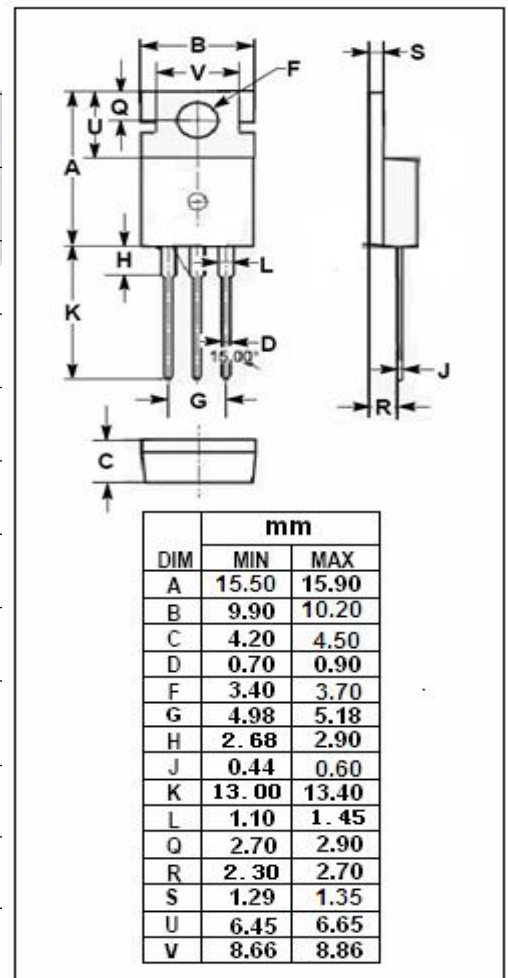
• DESCRIPTION

- Ideal for high frequency switching and sync. Rec.



• ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ C$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	150	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous	50	A
I_{DM}	Drain Current-Single Pulsed	200	A
P_D	Total Dissipation @ $T_c=25^\circ C$	150	W
T_j	Max. Operating Junction Temperature	175	$^\circ C$
T_{stg}	Storage Temperature	-55~175	$^\circ C$



• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(ch-c)}$	Channel-to-case thermal resistance	1	$^\circ C/W$
$R_{th(ch-a)}$	Channel-to-ambient thermal resistance	62	$^\circ C/W$

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ELECTRICAL CHARACTERISTICS

 T_C=25°C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V; I _D = 1mA	150			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ; I _D =90 μ A	2		4	V
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =10V; I _D =50A			20	mΩ
		V _{GS} =8V; I _D =25A			20	mΩ
I _{GSS}	Gate-Source Leakage Current	V _{GS} =20V; V _{DS} =0V			100	nA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =120V; V _{GS} = 0V			1	μ A
		V _{DS} =120V; V _{GS} = 0V; T _J = 125°C			100	μ A
V _{SD}	Diode forward voltage	I _F =50A; V _{GS} = 0 V			1.2	V